

## > Mechanical Specification:

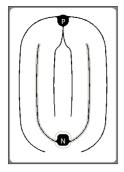
#### (1) Dimension

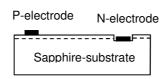
- Chip size: 30 mil x 43 mil (750  $\pm$  25  $\mu$ m x 1080  $\pm$  25  $\mu$ m)

- Thickness: 7.9 mil (200  $\pm$  10  $\mu m)$  - P bonding pad: 3.0 mil (77  $\pm$  10  $\mu m)$  - N bonding pad: 3.0 mil (77  $\pm$  10  $\mu m)$ 

#### (2) Metallization

Topside P electrode: Au alloyTopside N electrode: Au alloy





#### **Features:**

- · High radiant flux
- · Long operation life
- · Lambertian radiation
- · High anti-ESD level

#### **Applications:**

- . Lighting
- Backlighting

# > Electro-optical Characteristics at 25°C: (1)

Parameter	Symbol		Condition	Min.	Тур.	Max.	Unit
Forward Voltage	Vf1		If = 10μA	1.6	-	-	V
	Vf2		If = 60mA	-	2.8	2.9	V
Reverse Current	Ir		Vr = 5V	-	-	2.0	μΑ
Dominant Wavelength <sup>(2)</sup>	λd		If = 60mA	445	-	465	nm
Spectra Half-width	Δλ		If = 60mA	-	25	-	nm
Radiant Flux <sup>(3)(4)</sup>	Ро	A59	- If = 60mA	125	-	130	mW
		A60		130	-	135	

#### Note:

- (1) ESD protection during chip handling is recommended.
- (2) Basically, the wavelength span is 20nm; however, customers' special requirements are also welcome.
- (3) Radiant flux is determined by using an Ag-plated TO-can header without an encapsulant.
- (4) Radiant flux measurement allows a tolerance of ±15%.

# > Absolute Maximum Ratings:

Parameter	Symbol	Condition	Rating	Unit
Forward DC Current	If	Ta = 25°C	≤ 400	mA
Reverse Voltage	Vr	Ta = 25°C	≤ 5	V
Junction Temperature	Tj	-	≤ 125	°C
		Chip	-40 ~ +85	°C
Storage Temperature	Tstg	Chip-on-tape/storage	5 ~ 35	°C
		Chip-on-tape/transportation	-20 ~ +65	°C
Temperature during Packaging	-	-	280(<10sec)	°C

Note: Maximum ratings are package dependent. The above maximum ratings were determined using a Metal Core Printed Circuit Board (MCPCB) without an encapsulant. Stresses in excess of the absolute maximum ratings such as forward current and junction temperature may cause damage to the LED.

### > Characteristic Curves:

Fig.1 - Relative luminous Intensity vs. Forward Current

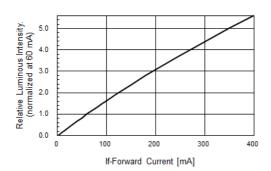


Fig.3 – Relative Intensity (@60mA) vs. Ambient Temperature

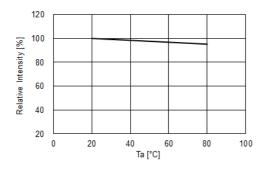


Fig.5 – Dominant Wavelength (@60mA) vs. Ambient Temperature

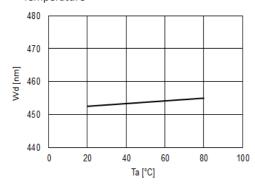


Fig.2 – Forward Current vs. Forward Voltage

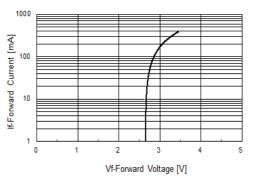


Fig.4 – Forward Voltage (@60mA) vs. Ambient Temperature

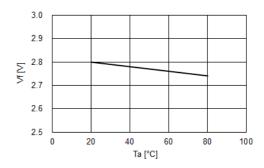


Fig.6 – Maximum Driving Forward DC Current vs. Ambient Temperature (De-rating based on Tj max. = 125°C)

